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|-----------|-----------|----------|
| APPROVED | O.G. FIG. | |
| BY | CLASS | SUBCLASS |
| DRAFTSMAN | | |

Title: Flip chip-in-leadframe package and process

Inventor: Pendse et al.
Appl. No. 09/802,443

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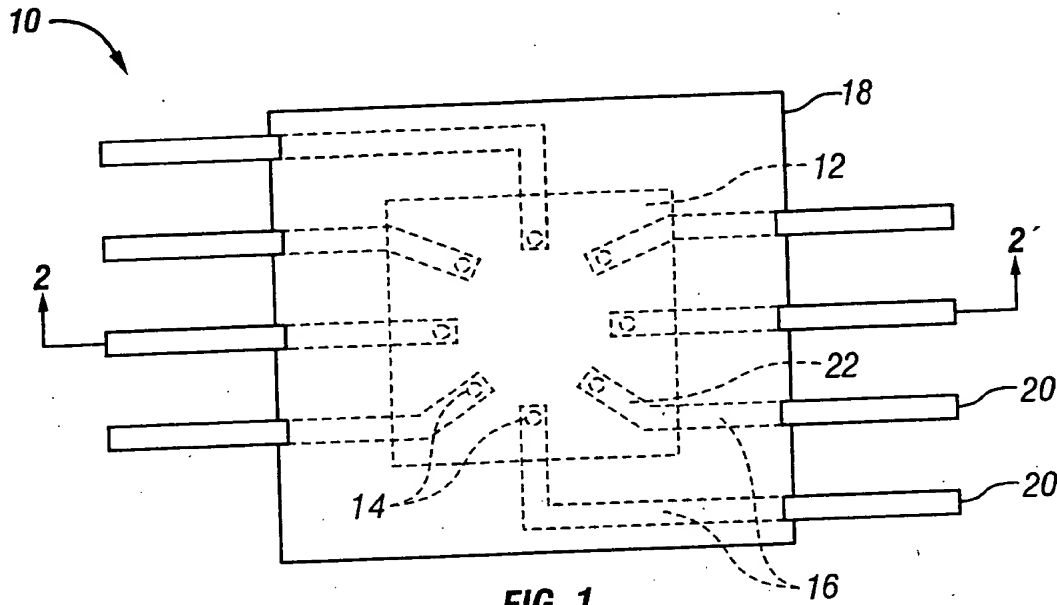


FIG. 1

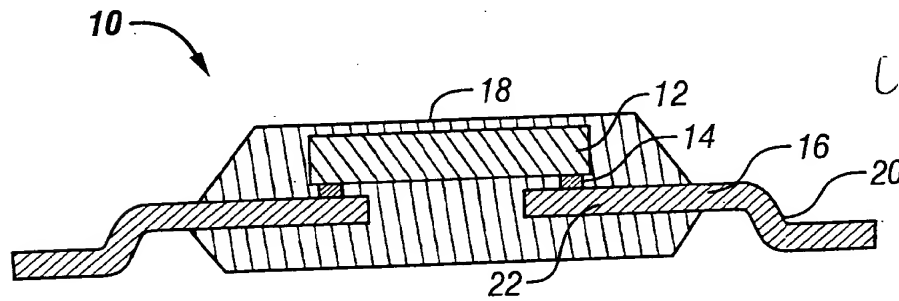


FIG. 2

Cavity down
up

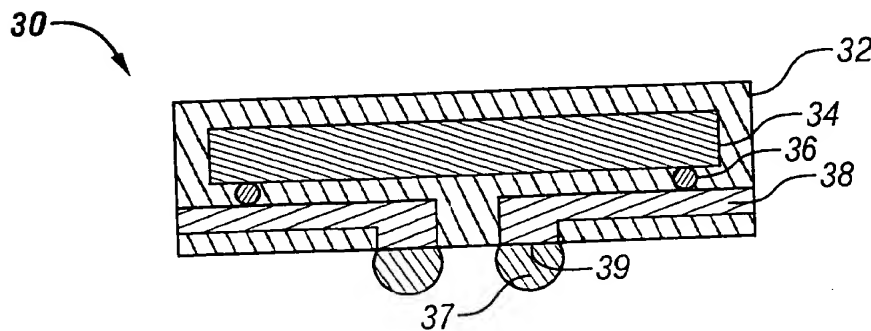


FIG. 3

Cavity down

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